

# **PRODUCT SPECIFICATION**

## MEC CERAMIC RESONATOR

## FREQUENCY COMPONENTS

ZTT-CS Series CERAMIC RESONATOR SPECIFICATION

MOBICON HOLDINGS LTD.					
Prepared By	Sign.	Approved By			
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# CERAMIC RESONATOR SPECIFICATION

#### PART NO.:

#### ZTTCS-8.00MT

#### ELECTRICAL CHARACTERISTICS

1.	Oscillation Frequency (Fosc)	8.00MHz $\pm 0.5\%$
2.	Resonant Impedance ( Ro )	25 Ohm
3.	Temperature Characteristics of	$\pm 0.5\%$ max. (-20°C ~ +80°C)
	Oscillation Frequency	
4.	Rating Voltage:	
	D.C. Voltage	6V
	Load Voltage	15Vpp
5.	Insulation Resistance	100 MOhm min. @ 10V DC
6.	Frequency Drift vs Temperature	$< \pm 0.3\%$
7.	Operating Temperature Range	$-20^{\circ}\mathrm{C} \sim +70^{\circ}\mathrm{C}$
8.	Storage Temperature Range	$-40^{\circ}\mathrm{C} \sim +85^{\circ}\mathrm{C}$
9.	Frequency Aging	$\pm 0.3\%$ max. for 10 years

#### M E A S U R E M E N T

#### Measurement Condition

The reference temperature shall be  $25^{\circ}C \pm 2^{\circ}C$ . The measurement shall be performed at the temperature range of  $5^{\circ}C \sim 35^{\circ}C$  unless otherwise the result is doubtful.

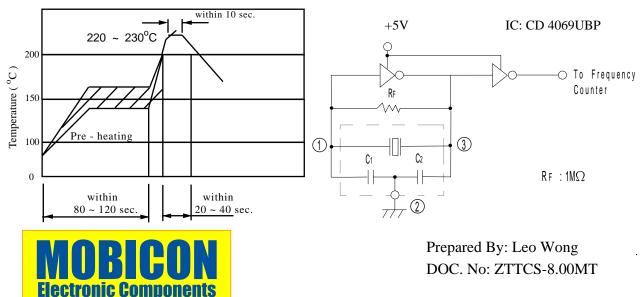
#### MEASUREMENT CIRCUIT AND EQUIPMENT

Oscillating frequency shall be measured by the standard test circuit.

Resonant impedance shall be measured by HP8751A Network Analyzer.

#### **Recommended Reflow Soldering Standard Conditions**

#### **Test Circuit**





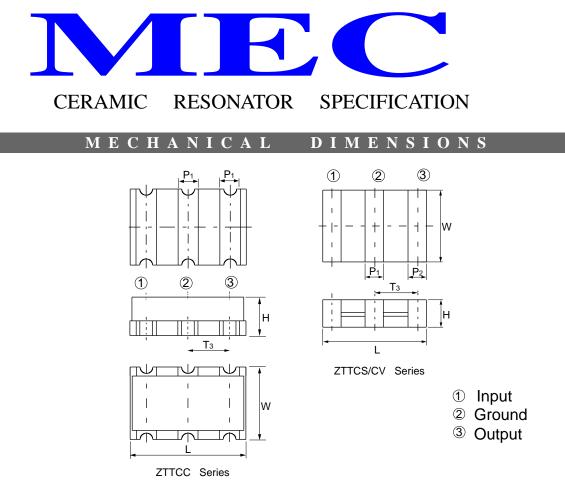
	CERAMIC RI	ESONATOR SPECIFICATIO	N
7	Temperature Cycling	Subject the resonator to -20°C for 30 min. followed by a high temperature of 85°C for 30 min. cycling shall be repeated 5 times with a transfer time of 15 seconds. At the room temperature for 1 hour prior to the measurement.	It shall fulfill the specifications in Table 1.
8	Solderability	Dipped in $230 \pm 5^{\circ}$ C seconds with resin flux (25wt% ethanol solution.)	The terminals shall be at least 95% covered by solder.
9	Board Bending	Mount a glass epoxy board (width = 40mm, thickness = 1.6mm), then bend it to 1mm displacement and keep it for 5 seconds. (See the following figure) $\downarrow^{PRESS}$ PRESS HEAD $\downarrow^{20}$ PRESS HEAD $\downarrow^{20}$ $\downarrow^{0}$ PRESS HEAD $\downarrow^{1.0 \pm 0.2}$ $\#^{45 \pm 2}$ $\#^{45 \pm 2}$	•

TABLE1

Item	Specification
Oscillation Frequency Change	$\Delta$ F/ Fosc $\leq 0.5\%$ max.
Resonant Impedance	Within $\pm 25 \ \Omega$

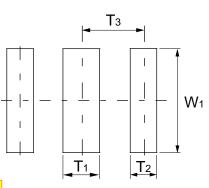


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Туре	DIMENSION (mm)								
Item	L	W	Н	P1	P2	<b>T</b> 1	T2	T3	W1
ZTTCC	7.4 ± 0.3	$3.4 \pm 0.3$	$1.8\pm0.3$	$1.2 \pm 0.3$	$1.2 \pm 0.3$	$1.5 \pm 0.3$	$1.7 \pm 0.3$	$2.5 \pm 0.3$	$4.0 \pm 0.3$
ZTTCS	4.7 ± 0.3	4.1 ± 0.2	1.6 ± 0.3	$1.0 \pm 0.4$	$0.8 \pm 0.4$	$1.3 \pm 0.2$	$0.8 \pm 0.2$	$1.95 \pm 0.2$	5.1 <u>+</u> 0.2
ZTTCV	$3.7\pm0.2$	3.1 ± 0.2	$1.2 \pm 0.3$	0.9 ± 0.3	0.7 ± 0.3	1.0 ± 0.2	$0.7 \pm 0.2$	1.5 ± 0.2	$4.1 \pm 0.2$

#### **RECOMMENED LAND PATTERN**





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#### PHYSICAL AND ENVIRONMENTAL CHARACTERISRICS

No.	Item	Condition	Performance Requirements	
1	Humidity	Keep the resonator at 90~95% RH for 96 $\pm$ release the resonator is condition for 1 hour p measurement.	It	
2	Vibration	Subject the resonator hours each in X, Y an amplitude of 1.5mm, shall be varied unifor limits of 10~55Hz.	shall	
3	Mechanical Shock	Drop the resonator rate wooden floor from the 100cm 3 times.	fulfill	
4	Soldering Test	Passed through the rest the following condition room temperature for measurement. Temperature at the surface of the substrate: Preheat $150 \pm 5^{\circ}C$ Peak $240 \pm 5^{\circ}C$	on, and left at 1 hour before Time $60 \pm 10$ sec. $10 \pm 3$ sec.	the specifications
5	High Temperature Exposure	Subject the resonator $96 \pm 4$ hours. Then re resonator into the roo 1 hour prior to the me	in Table 1.	
6	Low Temperature	Subject the resonator 96 $\pm$ 4 hours. Then re resonator into the roo 1 hour prior to the me		



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#### **REVIEW OF SPECIFICATIONS**

1) When something get doubtful with this specifications, we shall jointly work to get an agreement.

2) This specification limits the quality of the components as a single unit. Please insure the component is thoroughly evaluated in your application circuit.

3) Please do not use this component in any application that deviates from its intended use as noted within the specification. It may cause any mishaps.

4) Please return one of this specification after your signature of acceptance. In case of no return within 3 months from submission date. This specification should be treated as accepted.

#### When using our products, the following precautions should be taken.

 Safety designing of apparatus or a system allowing for failures of electronic components used in the system

In general, failures will occur in electronic components at a certain probability. MOBICON HOLDINGS LTD makes every effort to improve the quality and reliability of electronic component products. However, it is impossible to completely eliminate the probability of failures. Therefore, when using MOBICON HOLDINGS LTD electronic component products, systems should be carefully designed to ensure redundancy in the event of an accident which would result in injury or death, fire, or social damage, to ensure the prevention of the spread of fire, and the prevention of faulty operation.

- (2) Quality Level of various kinds of parts, and equipment in which the parts can be utilized Electronic components have a standard quality level unless otherwise specified.
- (3) This specifications is subject to change without notice. The contents of this specifications are based on data which is correct as of 2002, and they may be changed without notice. If our products are used for mass-production design, please enquire consult with a member of our company's sales staff by way of precaution.
- Reprinting and copying of this specifications without prior written permission from MOBICON HOLDINGS LTD are not permitted.
- (5) Industrial Property Problems

In the event any problems associated with industrial property of a third party arising as a result of the use of our products. MOBICON HOLDINGS LTD assumes no responsibility for problems other than problems directly associated with the constitution and manufacturing method of the products.



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